IEC 60749-4

Edition 2.0 2017-03

INTERNATIONAL STANDARD

Semiconductor devices – Mechanical and climatic test methods –
Part 4: Damp heat, steady state, highly accelerated stress test (HAST)

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 4: Damp heat, steady state, highly accelerated stress test (HAST)

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International Standard IEC 60749-4 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) clarification of requirements for temperature, relative humidity and duration detailed in Table 1;
b) recommendations that current limiting resistor(s) be placed in the test set-up to prevent test board or DUT damage;
c) allowance of additional time-to-test delay or return-to-stress delay.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2346/FDIS	47/2371/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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